

# **Fast Sinterglass Switching Rectifier**

#### **Features**

- High temperature metallurgically bonded construction
- · Hermetically sealed package
- · Cavity-free glass passivated junction
- 1.0 Ampere operation at T<sub>amb</sub> = 55 °C with no thermal runaway
- Typical I<sub>R</sub> less than 0.1 μA
- Capable of meeting environmental standards of MIL-S-19500
- · Fast switching for high efficiency
- High temperature soldering guaranteed: 350 °C/ 10 seconds, 0.375 " (9.5 mm) lead length, 5 lbs. (2.3 kg) tension



Case: JEDEC DO-204AP Solid glass body

Terminals: Solder plated axial leads, solderable per

MILSTD-750, Method 2026

Polarity: Color band denotes cathode end

Mounting Position: Any

Weight: 560 mg



17031

#### **Parts Table**

Part	Type differentiation				
1N4942	V <sub>RRM</sub> = 200 V				
1N4944	V <sub>RRM</sub> = 400 V				
1N4946	V <sub>RRM</sub> = 600 V				
1N4947	V <sub>RRM</sub> = 800 V				
1N4948	V <sub>RRM</sub> = 1000 V				

### **Absolute Maximum Ratings**

 $T_{amb}$  = 25 °C, unless otherwise specified

Parameter	Test condition	Sub type	Symbol	Value	Unit
Maximum repetitive peak reverse voltage		1N4942	$V_{RRM}$	200	V
		1N4944	$V_{RRM}$	400	V
		1N4946	$V_{RRM}$	600	V
		1N4947	$V_{RRM}$	800	V
		1N4948	V <sub>RRM</sub>	1000	V
Maximum RMS voltage		1N4942	V <sub>RMS</sub>	140	V
		1N4944	V <sub>RMS</sub>	280	V
		1N4946	V <sub>RMS</sub>	420	V
		1N4947	$V_{RMS}$	560	V
		1N4948	$V_{RMS}$	700	V
Maximum DC blocking voltage		1N4942	$V_{DC}$	200	V
		1N4944	$V_{DC}$	400	V
		1N4946	$V_{DC}$	600	V
		1N4947	$V_{DC}$	800	V
		1N4948	$V_{DC}$	1000	V
Maximum average forward rectified current	0.375 " (9.5 mm) lead length at $T_{amb}$ = 55 °C		I <sub>F(AV)</sub>	1.0	Α
Peak forward surge current	8.3 ms single half sine-wave superimposed on rated load (JEDEC Method)		I <sub>FSM</sub>	25	Α

Document Number 86092 www.vishay.com
Rev. 1, 12-Nov-02 1



### **Maximum Thermal Resistance**

T<sub>amb</sub> = 25 °C, unless otherwise specified

Parameter	Test condition	Sub type	Symbol	Value	Unit
Typical thermal resistance 1)			$R_{\theta}$	55	ô
Operating junction and storage temperature range			T <sub>J</sub> , T <sub>STG</sub>	- 65 to + 175	°C

<sup>1)</sup> Thermal resistance from junction to ambient at 0.375 " (9.5 mm) lead length, P.C.B. mounted

## **Electrical Characteristics**

 $T_{amb}$  = 25 °C, unless otherwise specified

Parameter	Test condition	Sub type	Symbol	Min	Тур.	Max	Unit
Minimum reverse breakdown voltage	I <sub>R</sub> = 50 μA	1N4942	V <sub>(BR)</sub>	220			V
	I <sub>R</sub> = 50 μA	1N4944	$V_{(BR)}$	440			V
	I <sub>R</sub> = 50 μA	1N4946	V <sub>(BR)</sub>	660			V
	I <sub>R</sub> = 50 μA	1N4947	V <sub>(BR)</sub>	880			V
	I <sub>R</sub> = 50 μA	1N4948	V <sub>(BR)</sub>	1100			V
Maximum instantaneous forward voltage	I <sub>F</sub> = 1 A		V <sub>F</sub>			1.3	V
	I <sub>F</sub> = 2 A, T <sub>amb</sub> = - 40 °C		V <sub>F</sub>			2.5	V
Maximum DC reverse current	at rated DC blocking voltage, T <sub>amb</sub> = 25 °C		I <sub>R</sub>			1.0	μΑ
	at rated DC blocking voltage, T <sub>amb</sub> = 175 °C		I <sub>R</sub>			500	μΑ
Maximum reverse recovery time	I <sub>F</sub> = 0.5 A, I <sub>R</sub> = 1.0 A, I <sub>rr</sub> = 25 A	1N4942	t <sub>rr</sub>			150	ns
	I <sub>F</sub> = 0.5 A, I <sub>R</sub> = 1.0 A, I <sub>rr</sub> = 25 A	1N4944	t <sub>rr</sub>			150	ns
	I <sub>F</sub> = 0.5 A, I <sub>R</sub> = 1.0 A, I <sub>rr</sub> = 25 A	1N4946	t <sub>rr</sub>			250	ns
	I <sub>F</sub> = 0.5 A, I <sub>R</sub> = 1.0 A, I <sub>rr</sub> = 25 A	1N4947	t <sub>rr</sub>			250	ns
	I <sub>F</sub> = 0.5 A, I <sub>R</sub> = 1.0 A, I <sub>rr</sub> = 25 A	1N4948	t <sub>rr</sub>			500	ns
Typical junction capacitance	V <sub>R</sub> = 4.0 V, f = 1 MHz		CJ		15		pF

## **Typical Characteristics** (T<sub>amb</sub> = 25°C unless otherwise specified)

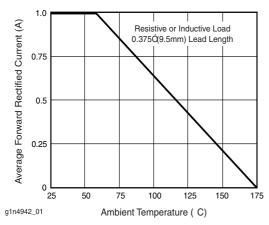


Figure 1. Maximum Forward Current Derating Curve

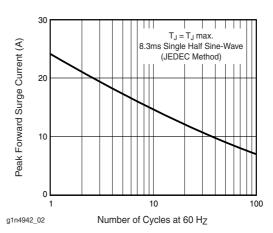


Figure 2. Maximum Non-Repetitive Peak Forward Surge Current



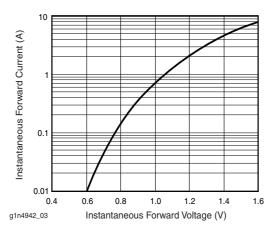


Figure 3. Typical Instantaneous Forward Characteristics

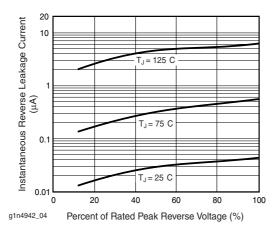


Figure 4. Typical Reverse Leakage Characteristics

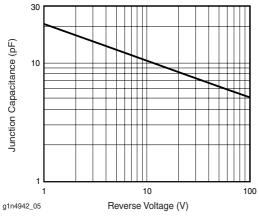
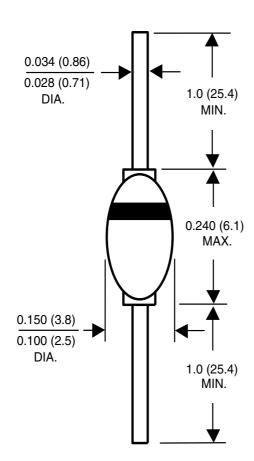


Figure 5. Typical Junction Capacitance

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## **Package Dimensions in mm**



17030



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- 1. Meet all present and future national and international statutory requirements.
- 2. Regularly and continuously improve the performance of our products, processes, distribution and operatingsystems with respect to their impact on the health and safety of our employees and the public, as well as their impact on the environment.

It is particular concern to control or eliminate releases of those substances into the atmosphere which are known as ozone depleting substances (ODSs).

The Montreal Protocol (1987) and its London Amendments (1990) intend to severely restrict the use of ODSs and forbid their use within the next ten years. Various national and international initiatives are pressing for an earlier ban on these substances.

Vishay Semiconductor GmbH has been able to use its policy of continuous improvements to eliminate the use of ODSs listed in the following documents.

- 1. Annex A, B and list of transitional substances of the Montreal Protocol and the London Amendments respectively
- 2. Class I and II ozone depleting substances in the Clean Air Act Amendments of 1990 by the Environmental Protection Agency (EPA) in the USA
- 3. Council Decision 88/540/EEC and 91/690/EEC Annex A, B and C (transitional substances) respectively.

Vishay Semiconductor GmbH can certify that our semiconductors are not manufactured with ozone depleting substances and do not contain such substances.

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> Vishay Semiconductor GmbH, P.O.B. 3535, D-74025 Heilbronn, Germany Telephone: 49 (0)7131 67 2831, Fax number: 49 (0)7131 67 2423

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